USB PORT TRANSIENT SUPPRESSORS

FEATURES

- Qualified for Automotive Applications
- Design to Protect Submicron 3-V or 5-V Circuits from Noise Transients
- Port ESD Protection Capability Exceeds:
  - 15-kV Human Body Model
  - 2-kV Machine Model
- Available in a WCSP Chip-Scale Package
- Stand-Off Voltage . . . 6 V Min
- Low Current Leakage . . . 1 μA Max at 6 V
- Low Capacitance . . . 35 pF Typ

APPLICATIONS

- USB 1.1 Host, Hub, or Peripheral Ports

DESCRIPTION

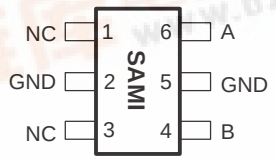
The SN65220 is a single transient voltage suppressor designed to provide electrical noise transient protection to universal serial bus (USB) 1.1 ports. Note that the input capacitance of the device makes it unsuitable for high-speed USB 2.0 applications.

Any cabled I/O can be subjected to electrical noise transients from various sources. These noise transients can cause damage to the USB transceiver and/or the USB ASIC if they are of sufficient magnitude and duration.

USB ports are typically implemented in 3-V or 5-V digital CMOS with limited ESD protection. The SN65220 can significantly increase the port ESD protection level and reduce the risk of damage to the circuits of the USB port.

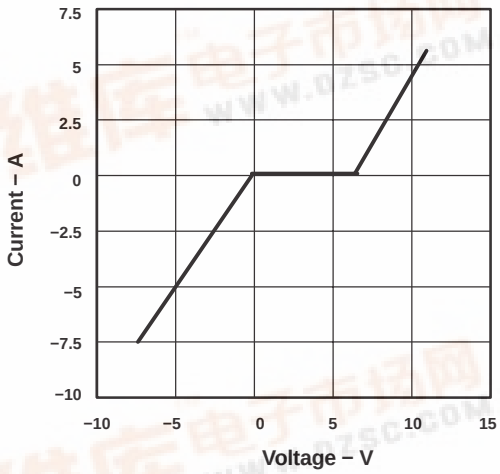
The IEC1000-4-2 ESD performance of the SN65220 is measured at the system level. Therefore, system design impacts the results of these tests. A high compliance level may be attained with proper board design and layout.

DBV
(TOP VIEW)†



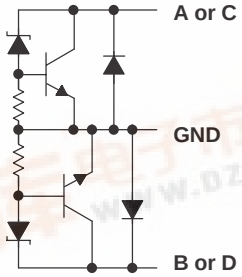
NC – No internal connection
†When read horizontally, pin 1 is the bottom left pin.

CURRENT vs VOLTAGE



NOTE A: Typical current versus voltage curve was derived using the IEC 1.2/50-μs surge waveform.

EQUIVALENT SCHEMATIC DIAGRAM



(One Suppressor Shown)

NOTE: All GND terminals should be connected to ground.

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

IEC1000-4-2 COMPLIANCE LEVEL

IEC1000-4-2 COMPLIANCE LEVEL	MAXIMUM TEST VOLTAGE	
	CONTACT DISCHARGE (kV)	AIR DISCHARGE (kV)
1	2	2
2	4	4
3	6	8
4	8	15

PACKAGE/ORDERING INFORMATION†

PRODUCT	SUPRESSORS	T_A	PACKAGE‡	PACKAGE DESIGNATOR	MARKED AS	ORDER NUMBER
SN65220	1	−40°C to 85°C	SOT23−6	DBV	SAMI	SN65220IDBVRQ1 (Mini Reel)

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

‡ Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted(1)

	UNIT
Continuous power dissipation	See Dissipation Rating Table
Electrostatic discharge	15 kV(2), 2 kV(3)
Peak power dissipation, $P_{D(peak)}$	60 W
Peak forward surge current, I_{FSM}	3 A
Peak reverse surge current, I_{RSM}	−9 A
Storage temperature range, T_{stg}	−65°C to 150°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Human Body Model − Tested in accordance with JEDEC Standard 22, Test Method A114−A.

(3) Charged Device Model − Tested in accordance with JEDEC Standard 22, Test Method C101.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$‡	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING
DBV	385 mW	3.1 mW/°C	246 mW	200 mW

‡ This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

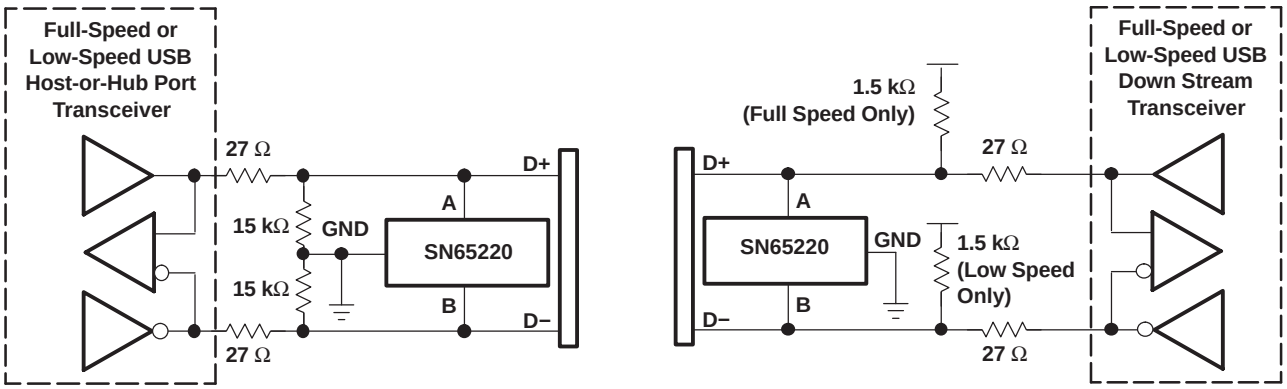
recommended operating conditions

	MIN	MAX	UNIT
Operating free-air temperature, T_A	−40	85	°C

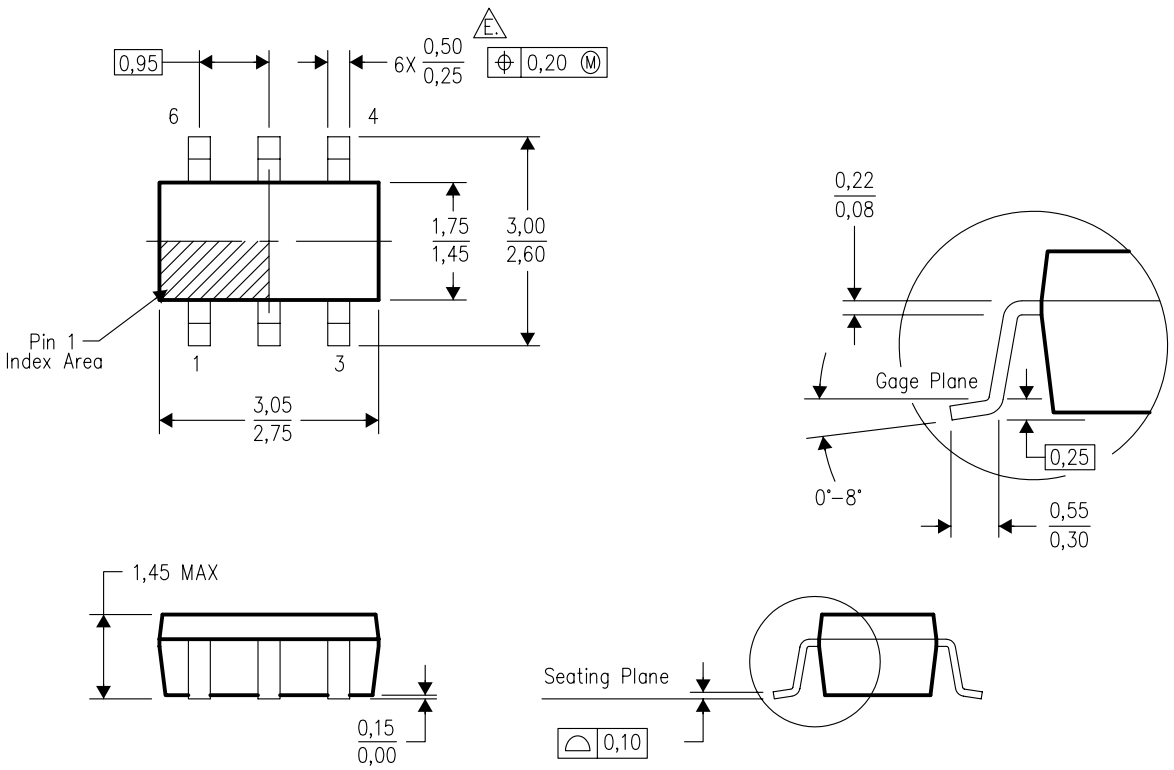
electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{lkg}	Leakage current	V_I = 6 V at A, B, C, or D terminals			1	μA
$V_{(BR)}$	Breakdown voltage	V_I = 1 mA at A, B, C, or D terminals	6.5	7	8	V
C_{IN}	Input capacitance to ground	V_I = 0.4 sin (4E6πt) + 0.5 V		35		pF

APPLICATION INFORMATION



DBV (R–PDSO–G6) PLASTIC SMALL–OUTLINE PACKAGE



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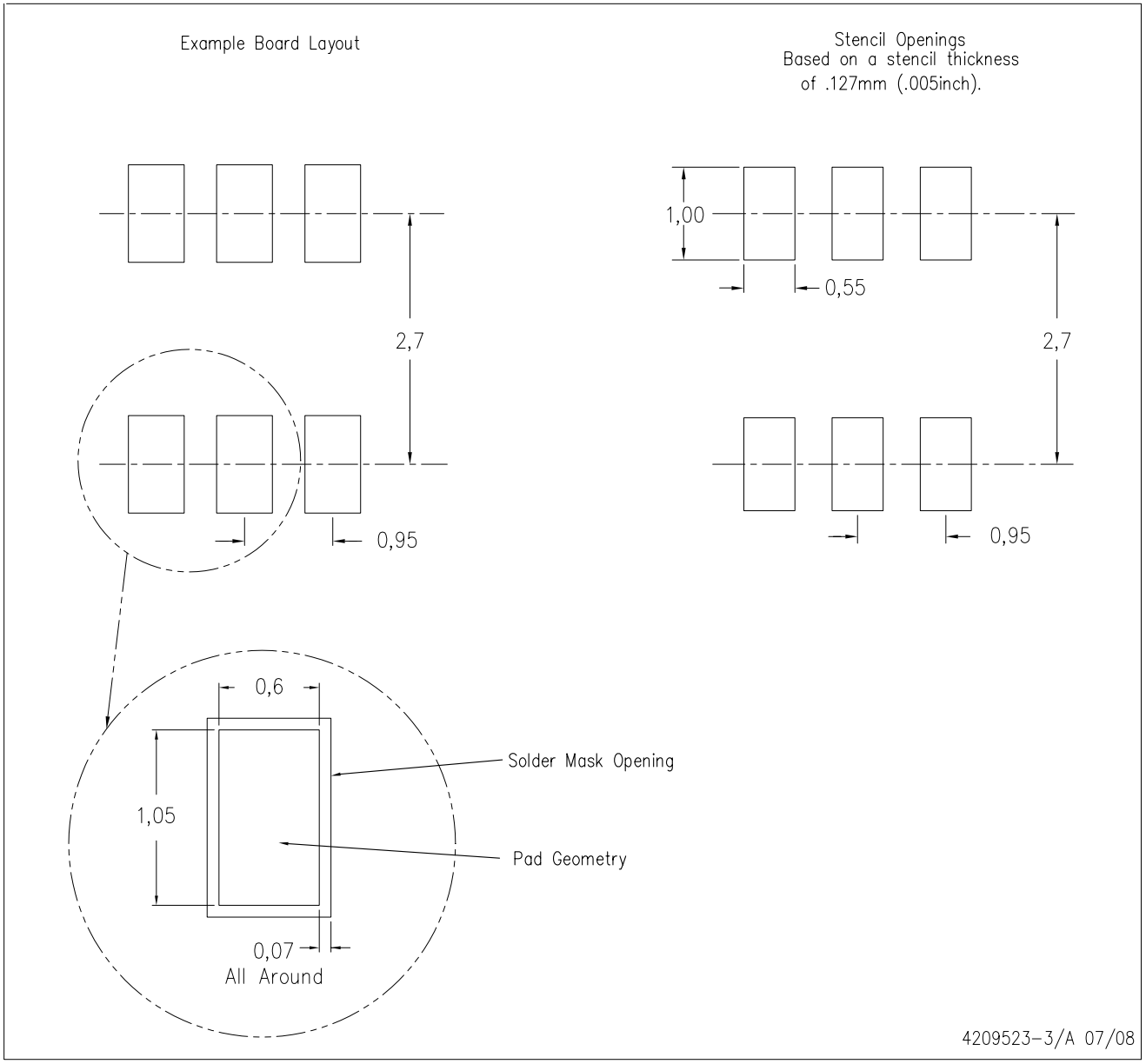
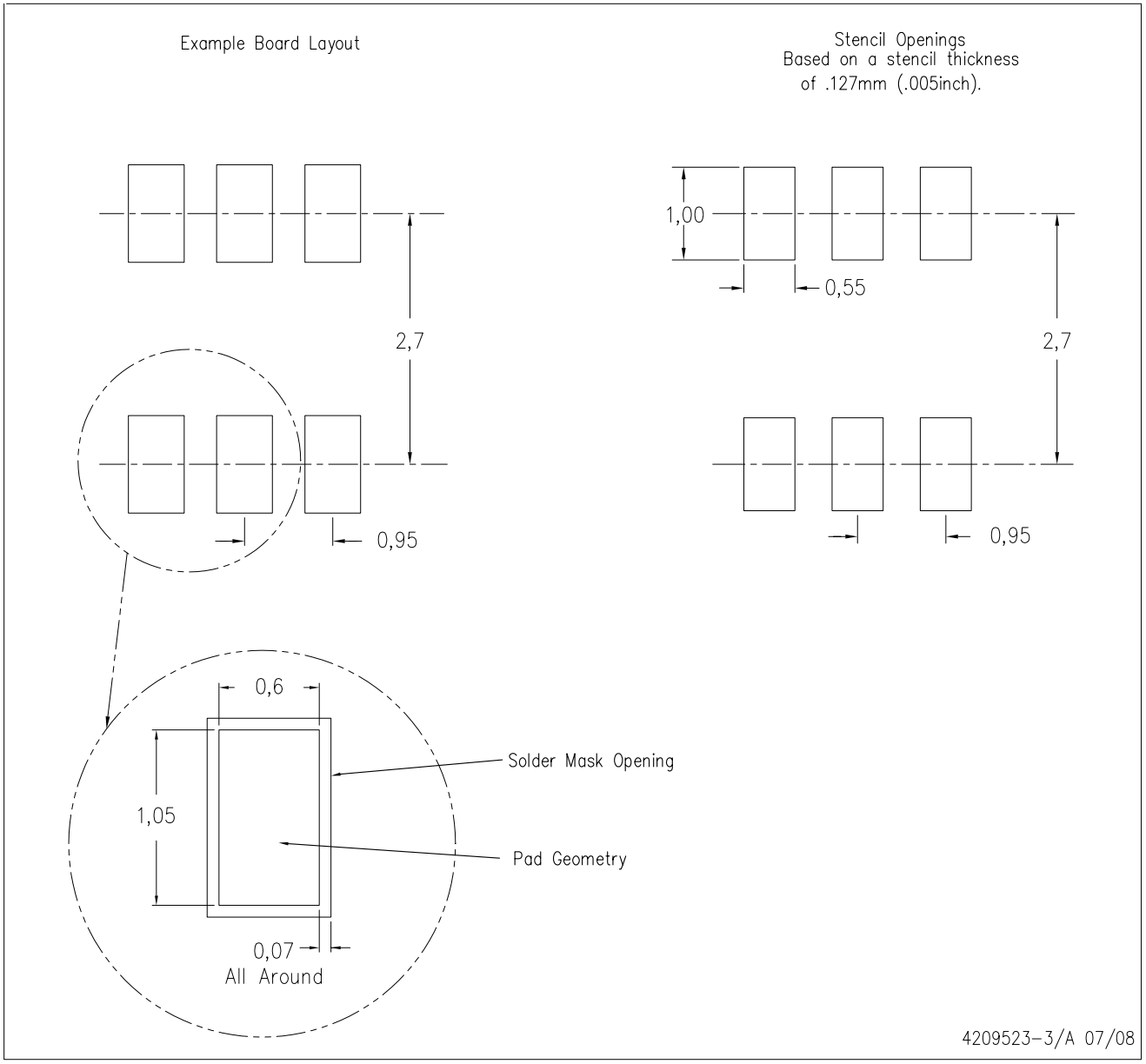
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
E. Falls within JEDEC MO–178 Variation AB, except minimum lead width.

DBV (R-PDSO-G6)



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC-7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DBV (R-PDSO-G6)



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